

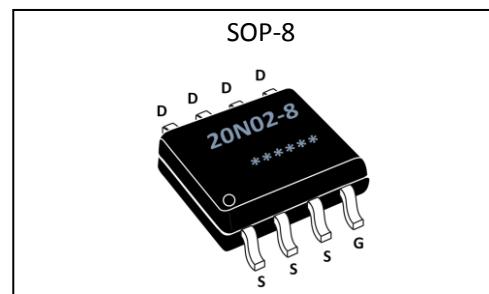
GL Silicon N-Channel Power MOSFET**General Description :**

The GL20N02-8 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is SOP-8, which accords with the RoHS standard.

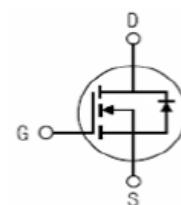
V_{DSS}	20	V
I_D	20	A
P_D	3	W
$R_{DS(ON)}\text{type}$	4.0	$\text{m}\Omega$

Features :

- $R_{DS(ON)} < 5.0 \text{ m}\Omega$ @ $V_{GS}=10V$ (Typ4.0mΩ)
- High density cell design for ultra low $R_{ds(on)}$
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

**Applications :**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Inner Equivalent Principium Chart**Absolute ($T_c=25^\circ\text{C}$ unless otherwise specified):**

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	20	V
I_D	Continuous Drain Current	20	A
I_{DM}	Pulsed Drain Current	60	A
V_{GS}	Gate-to-Source Voltage	± 12	V
P_D	Power Dissipation	3	W
E_{AS}	Single pulse avalanche energy ^{a5}	200	mJ
T_J, T_{stg}	Operating Junction and Storage Temperature Range	175, -55 to 150	$^\circ\text{C}$



GL20N02-8

无锡光磊电子科技有限公司

GL Silicon N-Channel Power MOSFET

Electrical Characteristics (Tc= 25°C unless otherwise specified) :

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V _{DSS}	Drain to Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20	--	--	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =20V, V _{GS} = 0V, T _a = 25°C	--	--	1.0	μA
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =+12V	--	--	0.1	μA
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =-12V	--	--	-0.1	μA

ON Characteristics ^{a3}						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R _{DSON} 1	Drain-to-Source On-Resistance	V _{GS} =10V,I _D =10A	--	4.0	5.0	mΩ
R _{DSON} 2	Drain-to-Source On-Resistance	V _{GS} =4.5V,I _D =10A	--	4.4	5.5	mΩ
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =250μA	0.5		1.2	V
Pulse width tp≤380μs,δ≤2%						

Dynamic Characteristics ^{a4}						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g _f	Forward Transconductance	V _{DS} =5V,I _D =10A	15	--	--	S
C _{iss}	Input Capacitance	V _{GS} =0V,V _{DS} =10V	--	2000	--	pF
C _{oss}	Output Capacitance	f=1.0MHz	--	500	--	
C _{rss}	Reverse Transfer Capacitance		--	210	--	

Resistive Switching Characteristics ^{a4}						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =10V,I _D =25A V _{GS} =5V,R _G =1.8Ω	--	7	--	ns
t _r	Rise Time		--	18	--	
t _{d(OFF)}	Turn-Off Delay Time		--	30	--	
t _f	Fall Time		--	17	--	
Q _g	Total Gate Charge	V _{DD} =10V, I _D =25A V _{GS} =10V	--	28	--	nC
Q _{gs}	Gate to Source Charge		--	7	--	
Q _{gd}	Gate to Drain ("Miller")Charge		--	6.8	--	

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Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I _S	Continuous Source Current ^{a2} (Body Diode)		--	--	20	A
V _{SD}	Diode Forward Voltage ^{a3}	I _S =20A, V _{GS} =0V	--	--	1.2	V

Symbol	Parameter	Typ.	Units
R _{θJA}	Junction-to-Ambient	42	°C/W

^{a1} : Repetitive Rating: Pulse width limited by maximum junction temperature.

^{a2} : Surface Mounted on FR4 Board, t≤10sec.

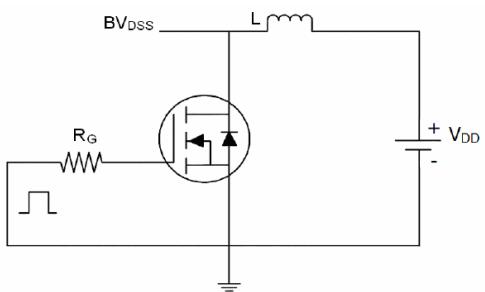
^{a3} : Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%.

^{a4} : Guaranteed by design, not subject to production

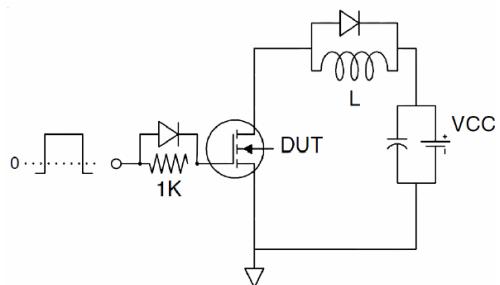
^{a5} : EAS condition : T_j=25°C, V_{DD}=15V, V_{GS}=10V, L=1.0mH, R_g=25Ω

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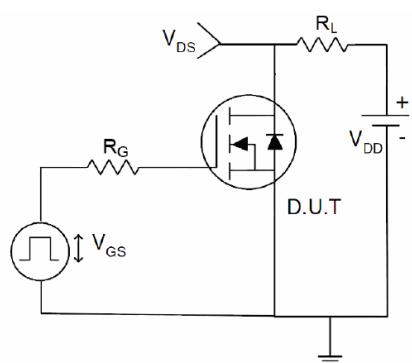
Test circuit

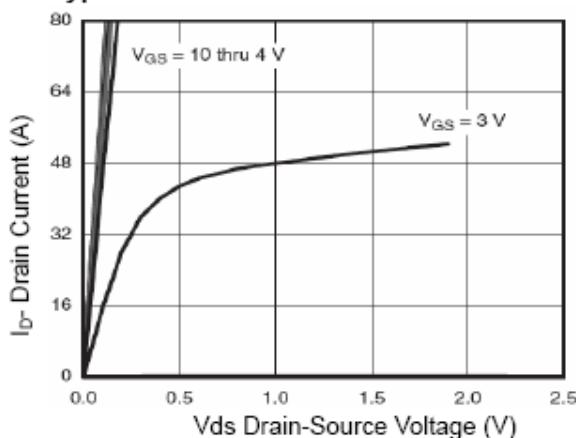
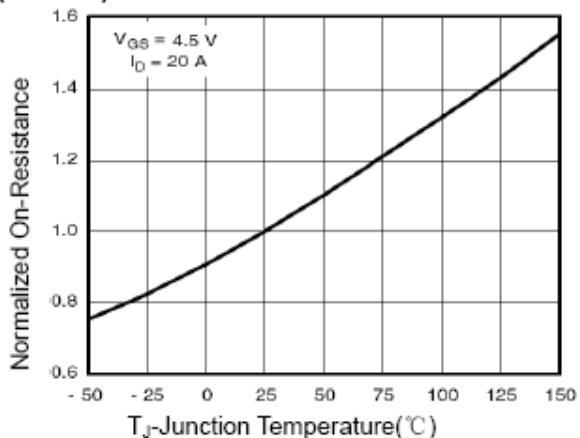
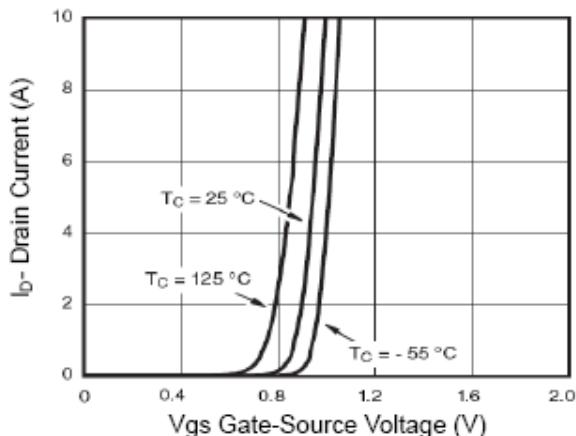
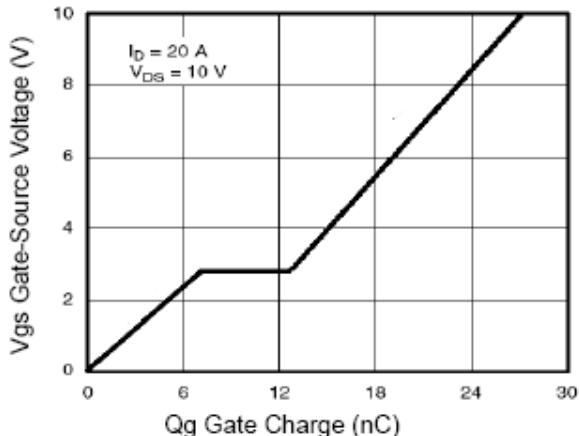
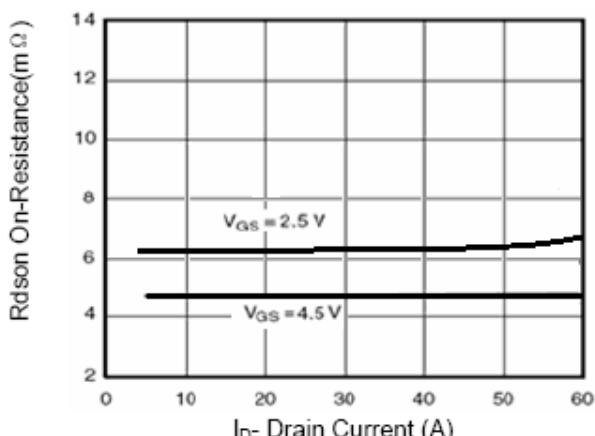
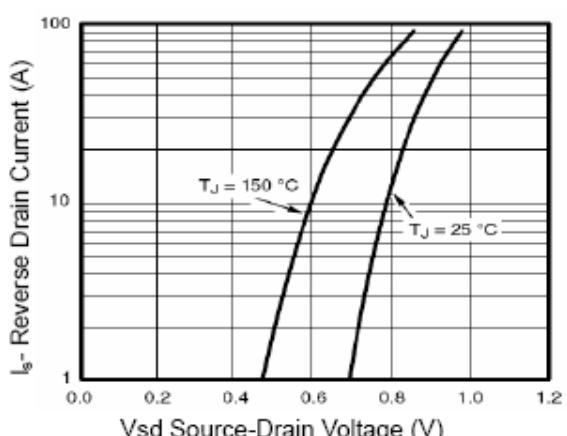
1) E_{AS} test Circuits

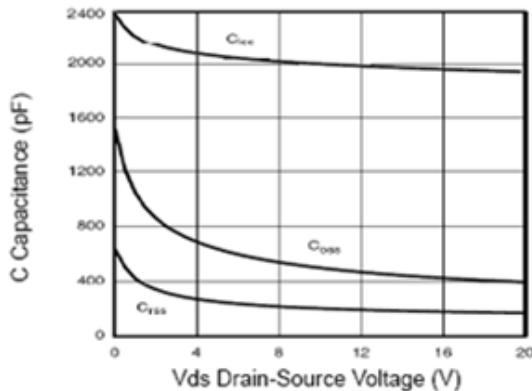
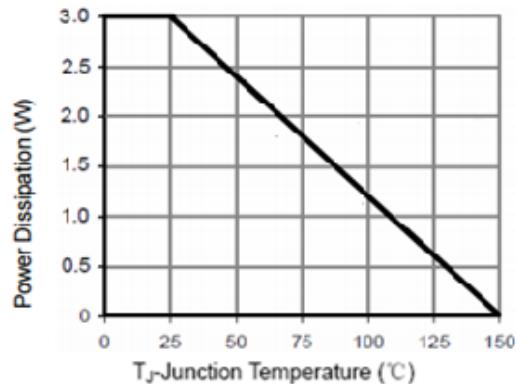
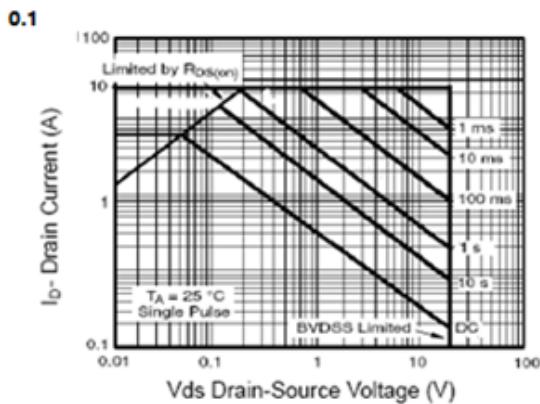
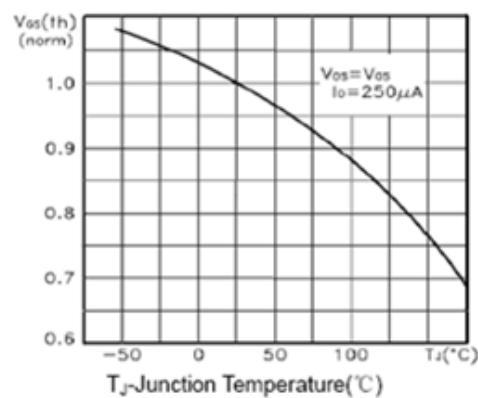
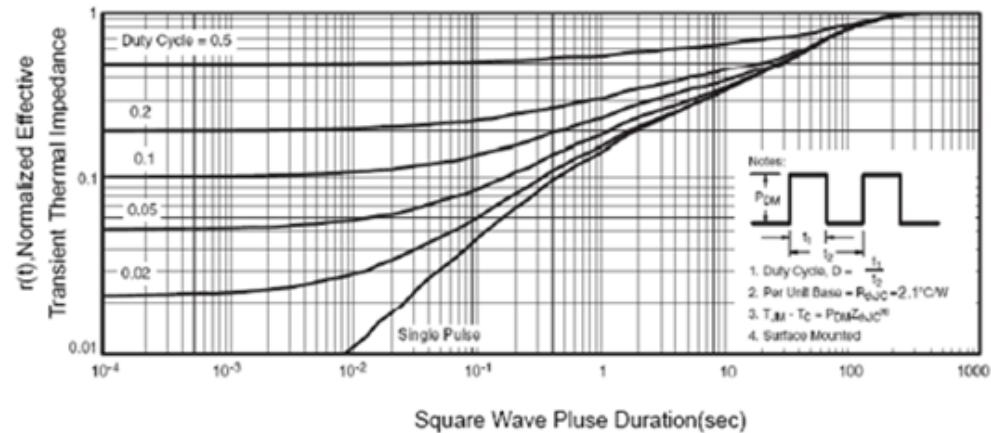
2) Gate charge test Circuit:



3) Switch Time Test Circuit:



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Characteristics Curve :

Figure 1 Output Characteristics

Figure 4 Rdson-JunctionTemperature

Figure 2 Transfer Characteristics

Figure 5 Gate Charge

Figure 3 Rdson- Drain Current

Figure 6 Source- Drift Diode Forward

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Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 V_{GS(th)} vs Junction Temperature

Figure 11 Normalized Maximum Transient Thermal Impedance

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